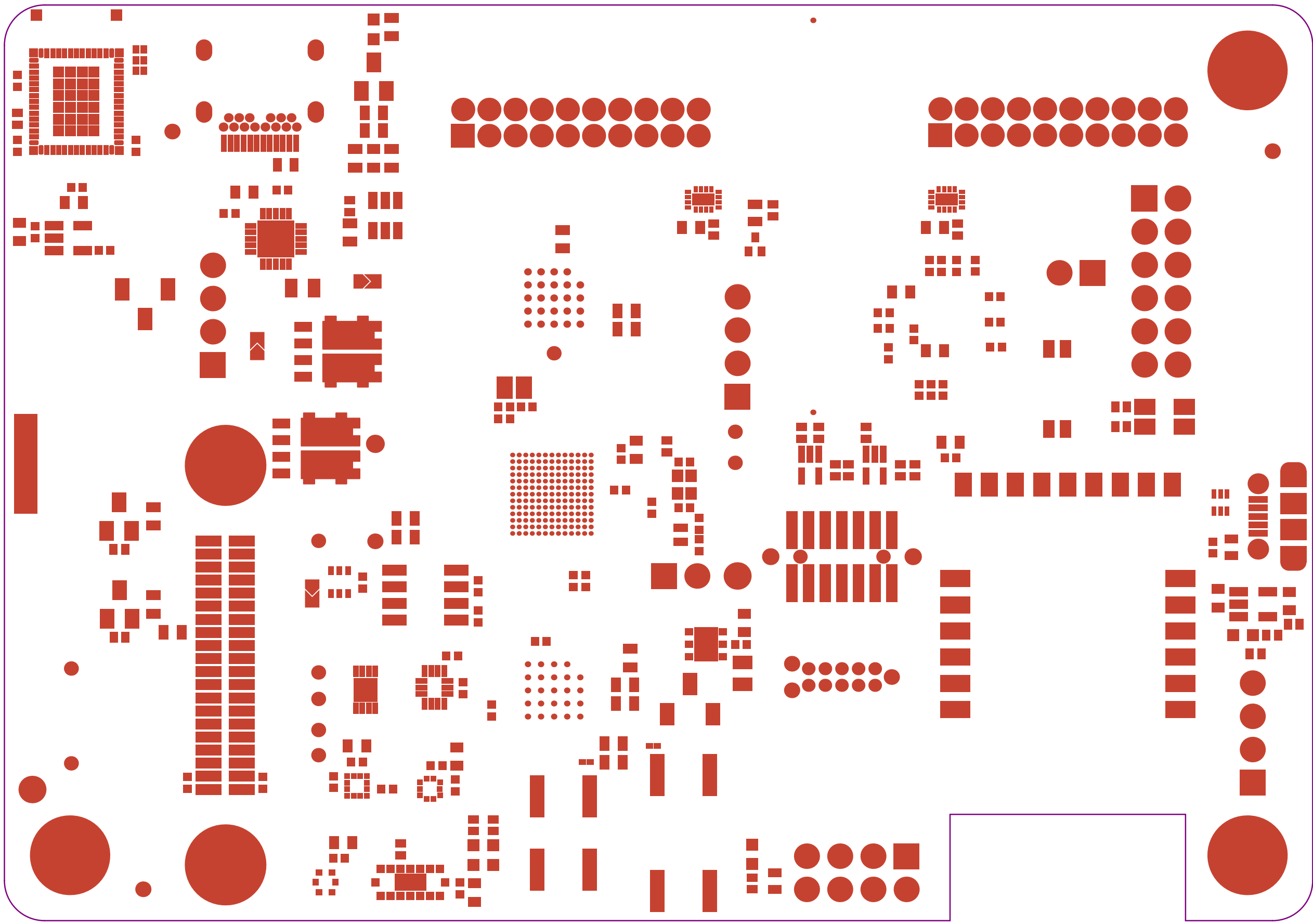


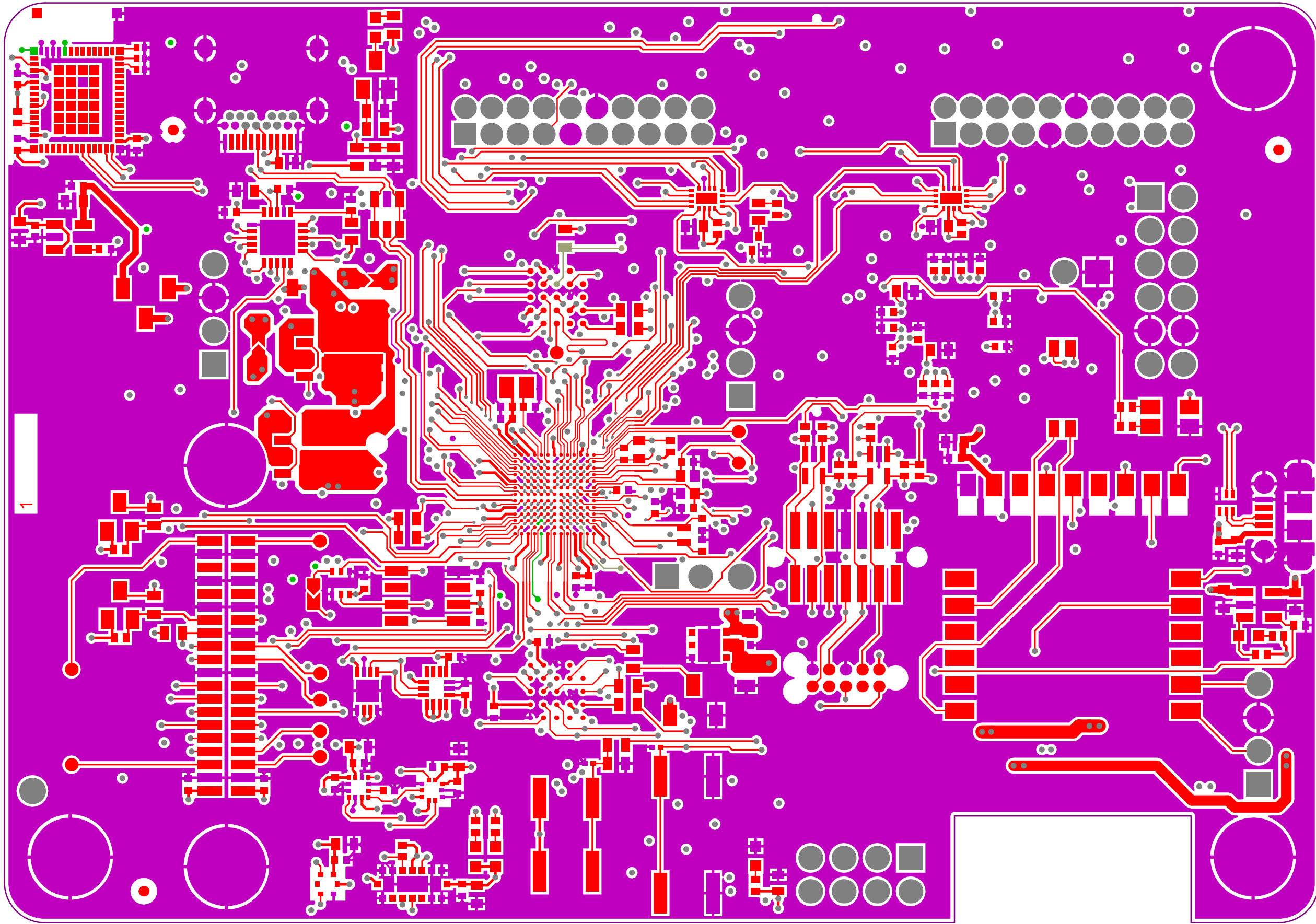
Top Overlay

.GTO



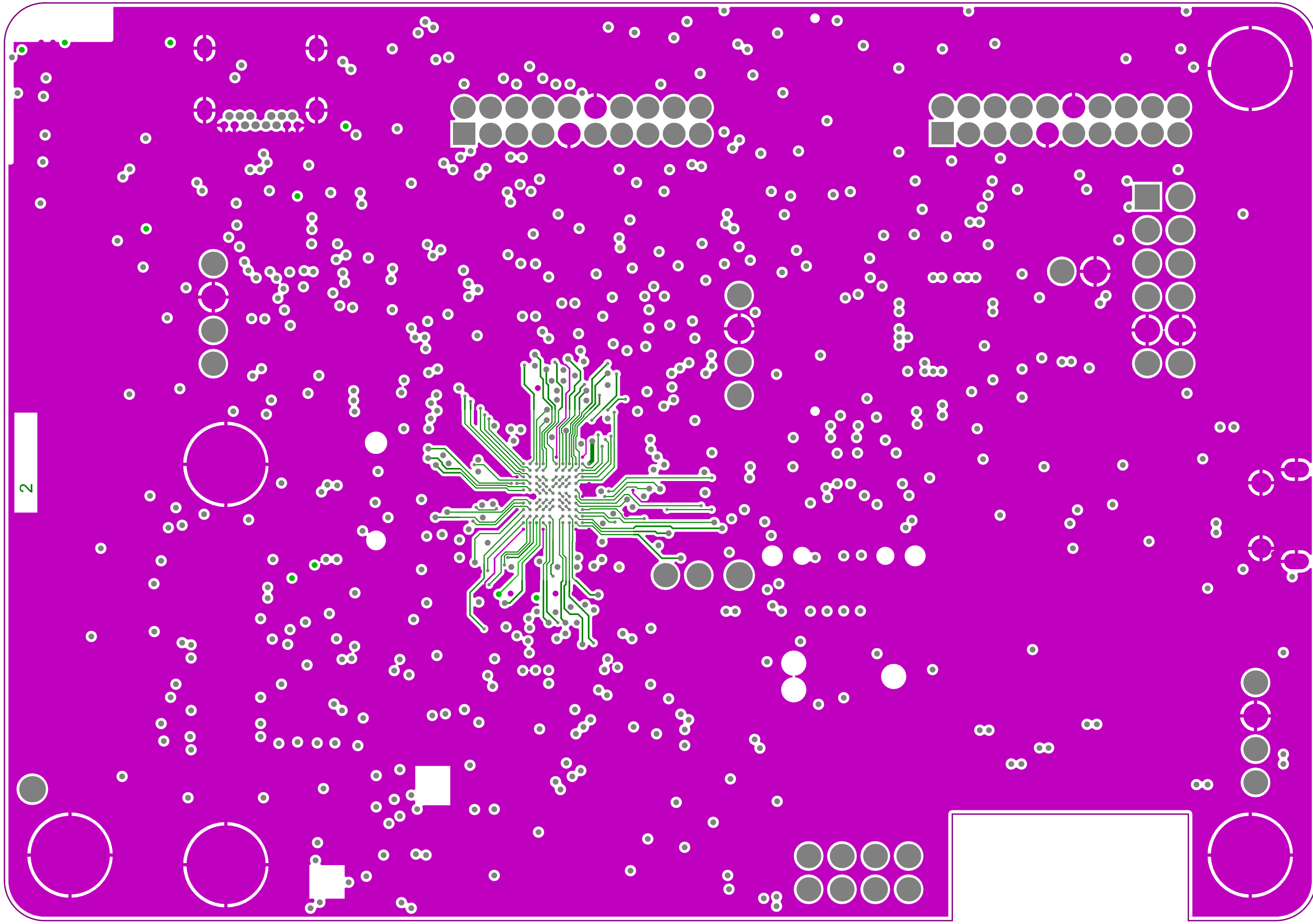
Top Solder

.GTS



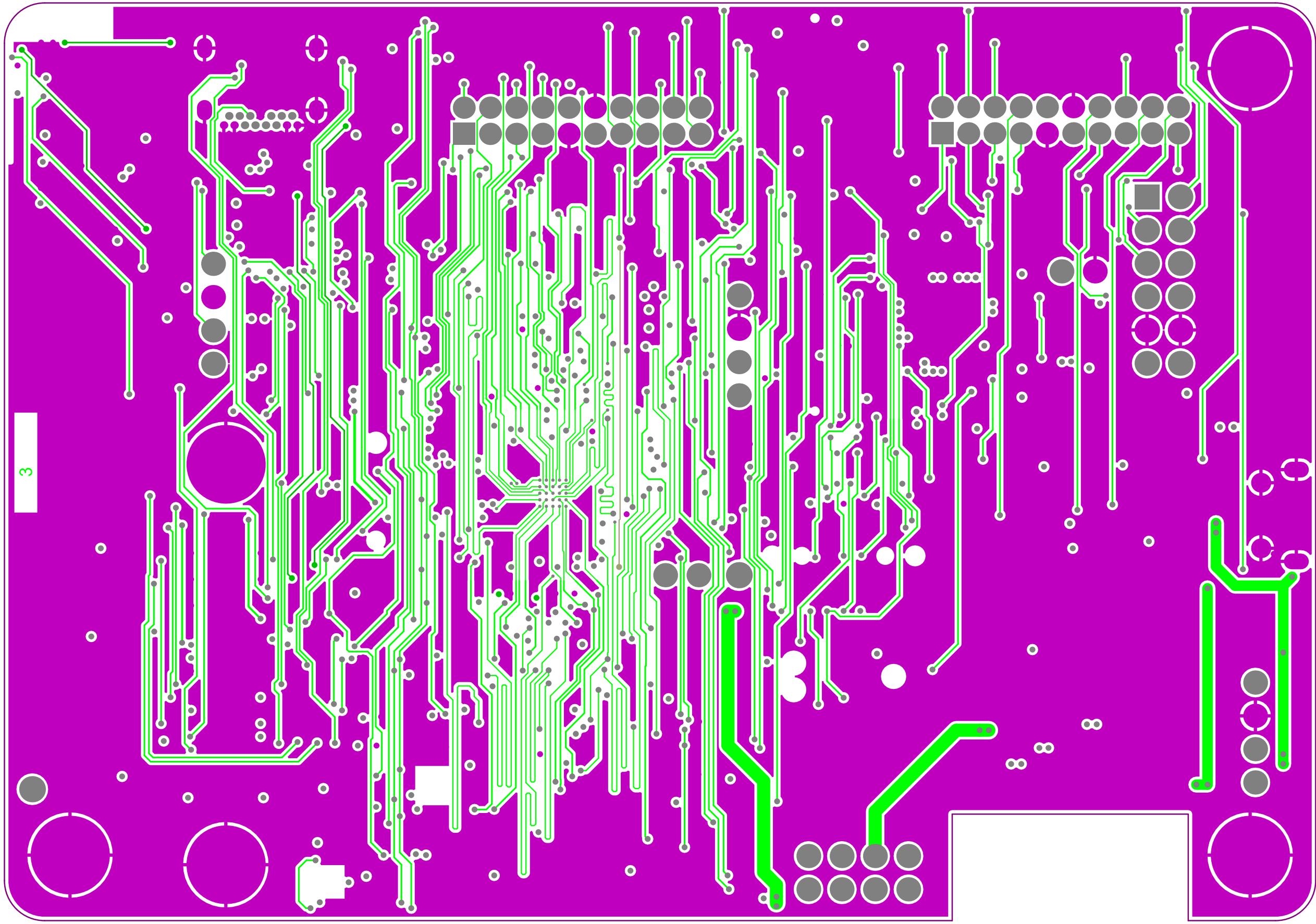
Top Layer

.GTL



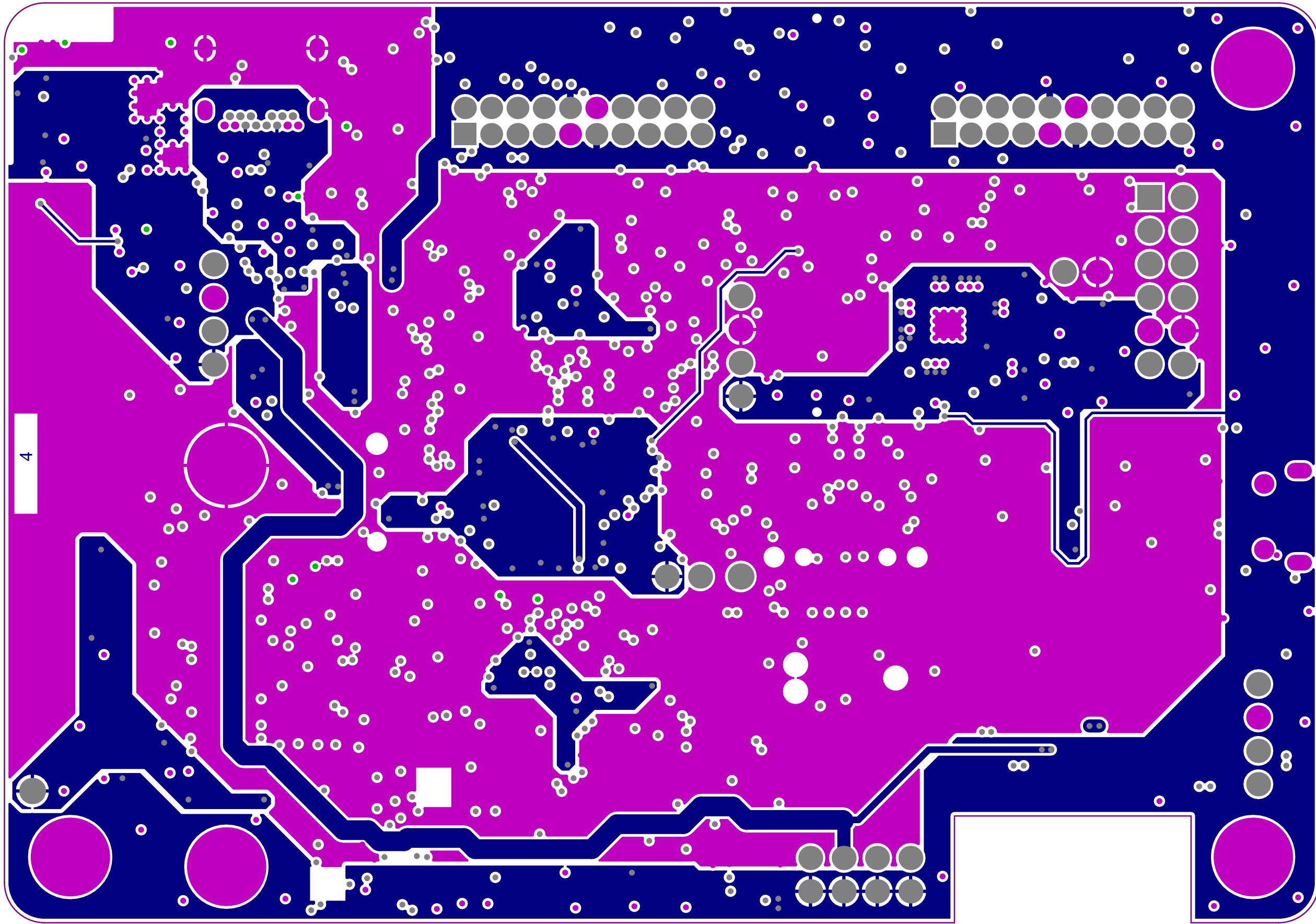
Signal Layer 1

.G1



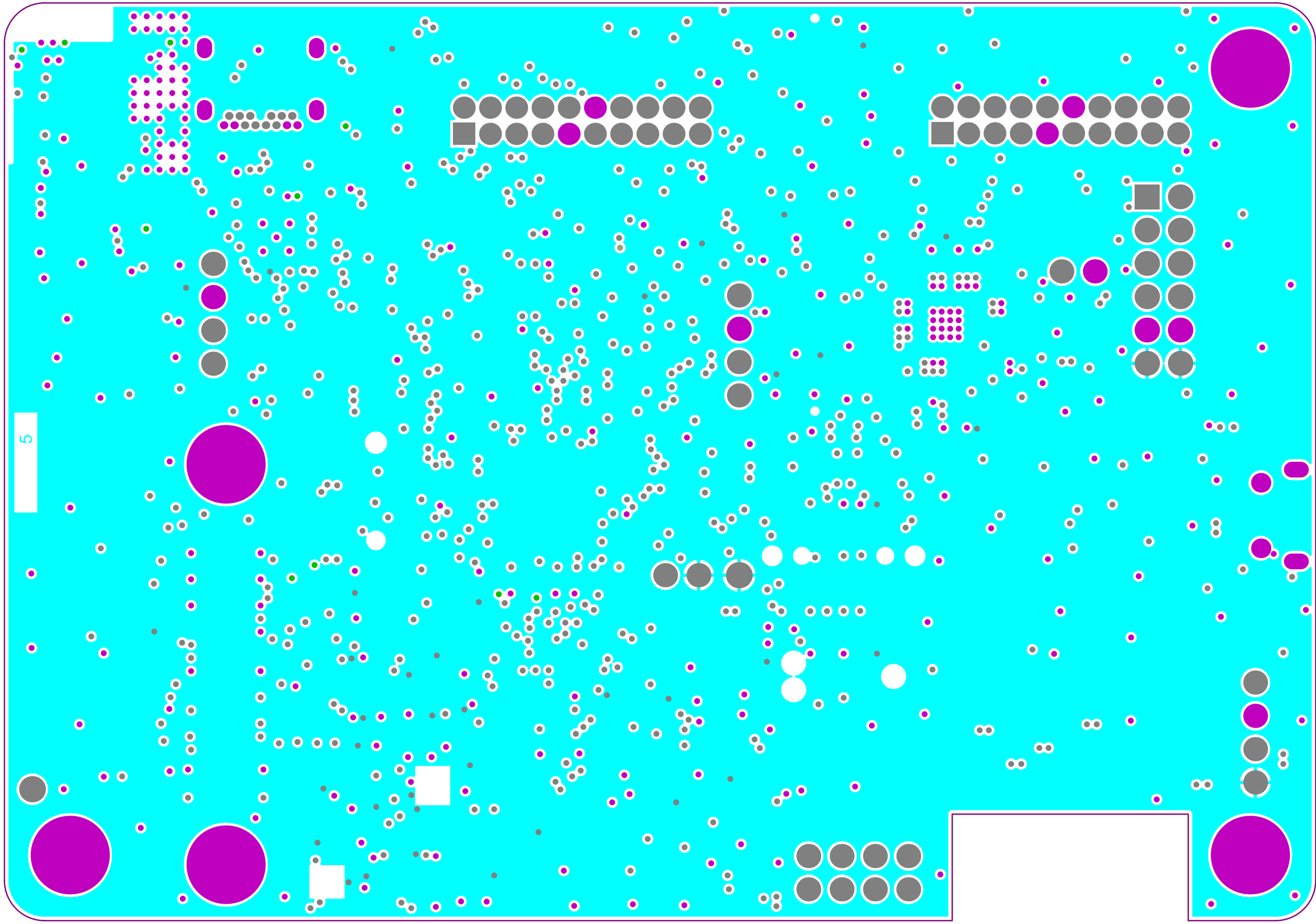
Signal Layer 2

.G2



Signal Layer 3

.G3

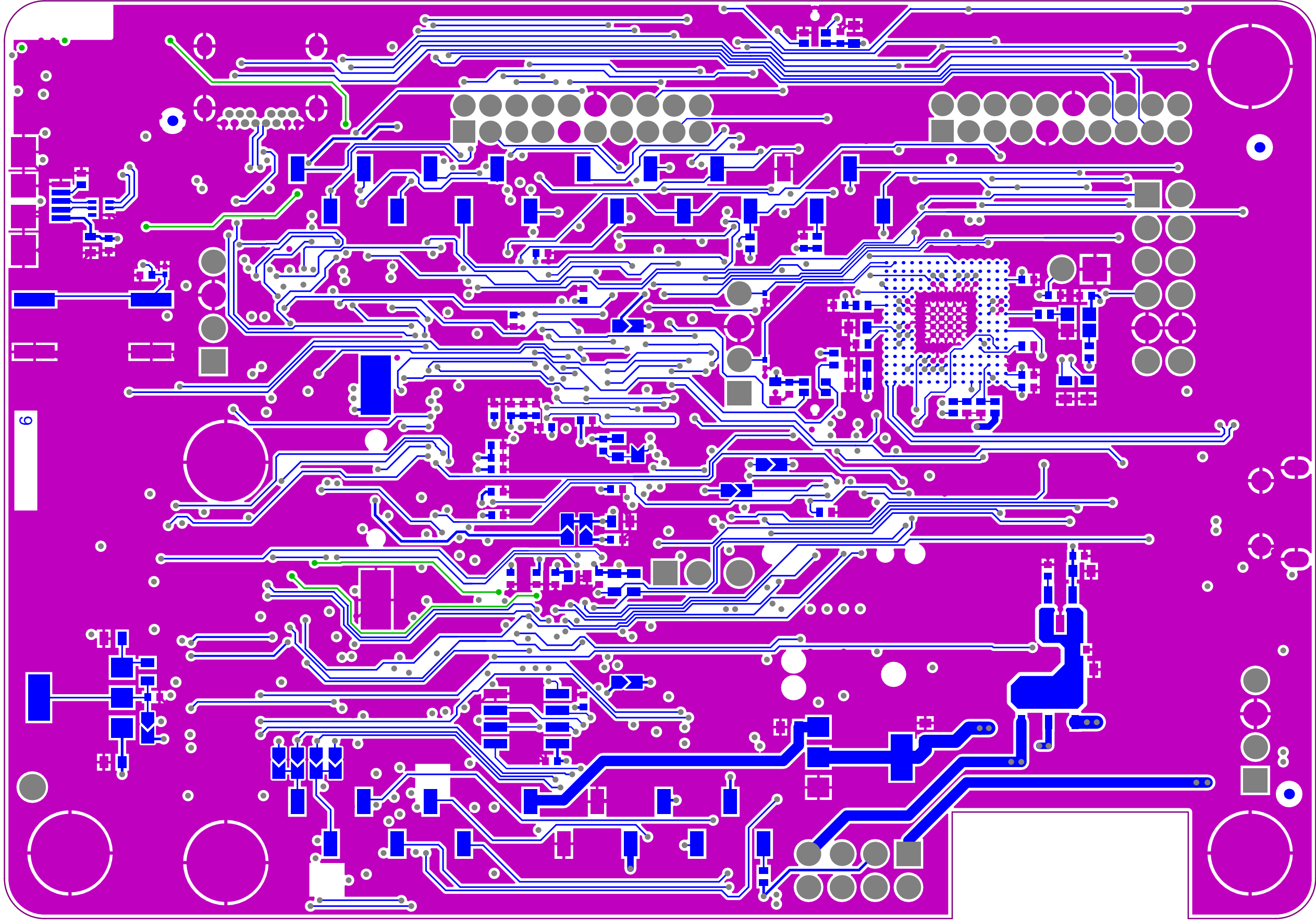


Signal Layer 4

.G4

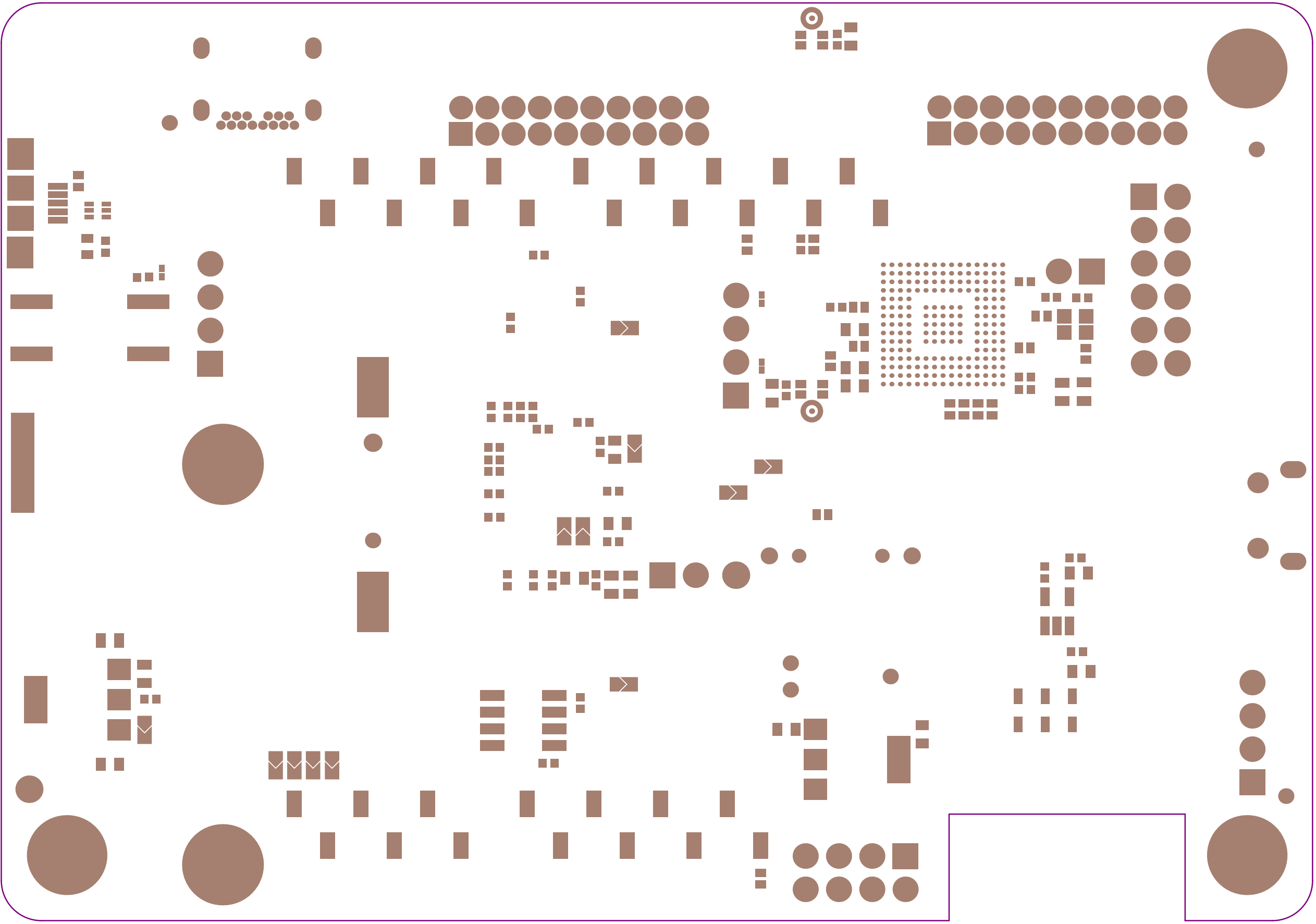
.GBL

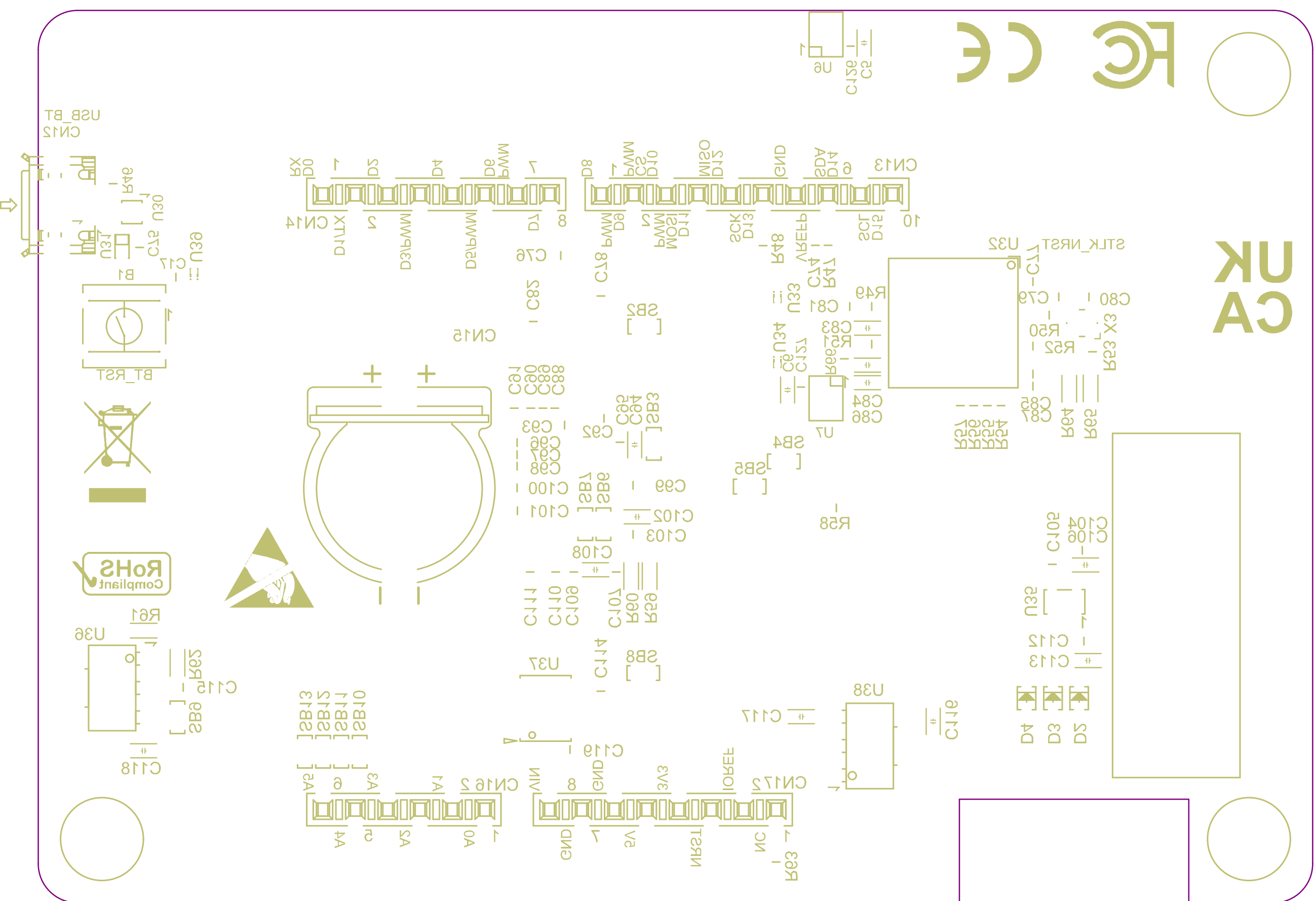
Bottom Layer



.GBS

Bottom Solder





Bottom Overlay

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☐ NO

☒ BLUE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☒ TG-170

☒ TG-150

☐ TG-140

☐ RED

☐ BLACK

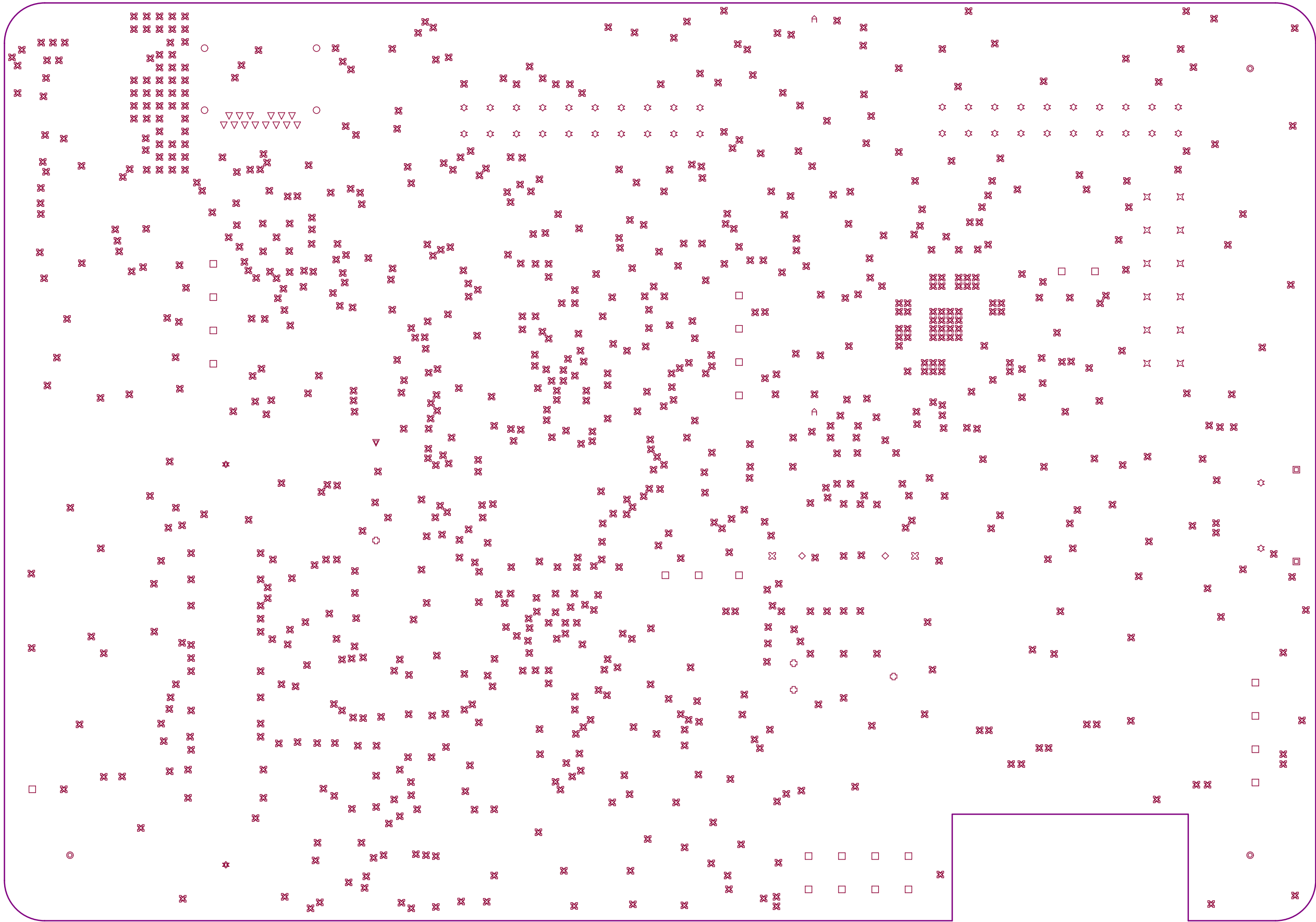
☐ IMMERSION TIN

☐ GOLDEN FINGER

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

MINIMUM PARAMETERS
DEFAULT TRACKS : 0.12mm GAPS : 0.12mm
BGA (MCU) : TRACKS : 0.08mm GAPS : 0.085mm
BGA (STLink) : TRACKS : 0.09mm GAPS : 0.09mm

THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY)



Drill Drawing

.DRL

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3,5	
1	Top Layer	Copper	0,035mm		
	Dielectric 1	TU-768P	0,070mm	3,85	
2	Signal Layer 1	Copper	0,035mm		
	Dielectric2	TU-768P	0,070mm	3,85	
3	Signal Layer 2	Copper	0,035mm		
	Dielectric3	TU-768	1,000mm	4,5	
4	Signal Layer 3	Copper	0,035mm		
	Dielectric4	TU-768P	0,070mm	3,85	
5	Signal Layer 4	Copper	0,035mm		
	Dielectric5	TU-768P	0,070mm	3,85	
6	Bottom Layer	Copper	0,035mm		
	Bottom Solder	Solder Resist	0,015mm	3,5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
▽	1	1,300mm (51,18mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
⌒	2	0,325mm (12,80mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
▣	2	0,600mm (23,62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded
◇	2	0,970mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
⊗	2	1,190mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
⊛	2	3,200mm (125,98mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
◎	3	3,500mm (137,79mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
○	4	0,450mm (17,72mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded
⊕	4	1,100mm (43,31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
✕	12	1,100mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
▽	14	0,400mm (15,75mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
▣	26	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
⊛	42	0,900mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
✕	174	0,100mm (3,94mil)	PTH	Round	(Mixed)	Via	Rounded
⊗	915	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	1205 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout